

AMENDMENTS TO THE SPECIFICATION

Please amend the Title of invention as follows:

High-Density, Zero-Height, Free-Floating Interconnect ~~Method and Apparatus~~ System

Please replace the current Abstract with the following replacement Abstract:

A system provides a zero interconnection height in a board-to-board interconnect while maintaining efficient space allocation for multiple axis connections by providing a floating connection in one plane thereby enabling a connection in another plane. A first circuit board having a first plurality of through-holes is aligned with a second circuit board having a second plurality of through-holes so that the first plurality of through-holes is matched with the second plurality of through-holes. An interconnection height of zero is provided between the first circuit board and the second circuit board. At least one pass-through socket, which includes pass-through socket through-holes, is aligned with the combination of the first circuit board and second circuit board. One or more pins disposed on a pin header are inserted through the pass-through socket, the first circuit board, and the second circuit board.